

EE671: VLSI DESIGN

AUTUMN 2024-25

LECTURE-1

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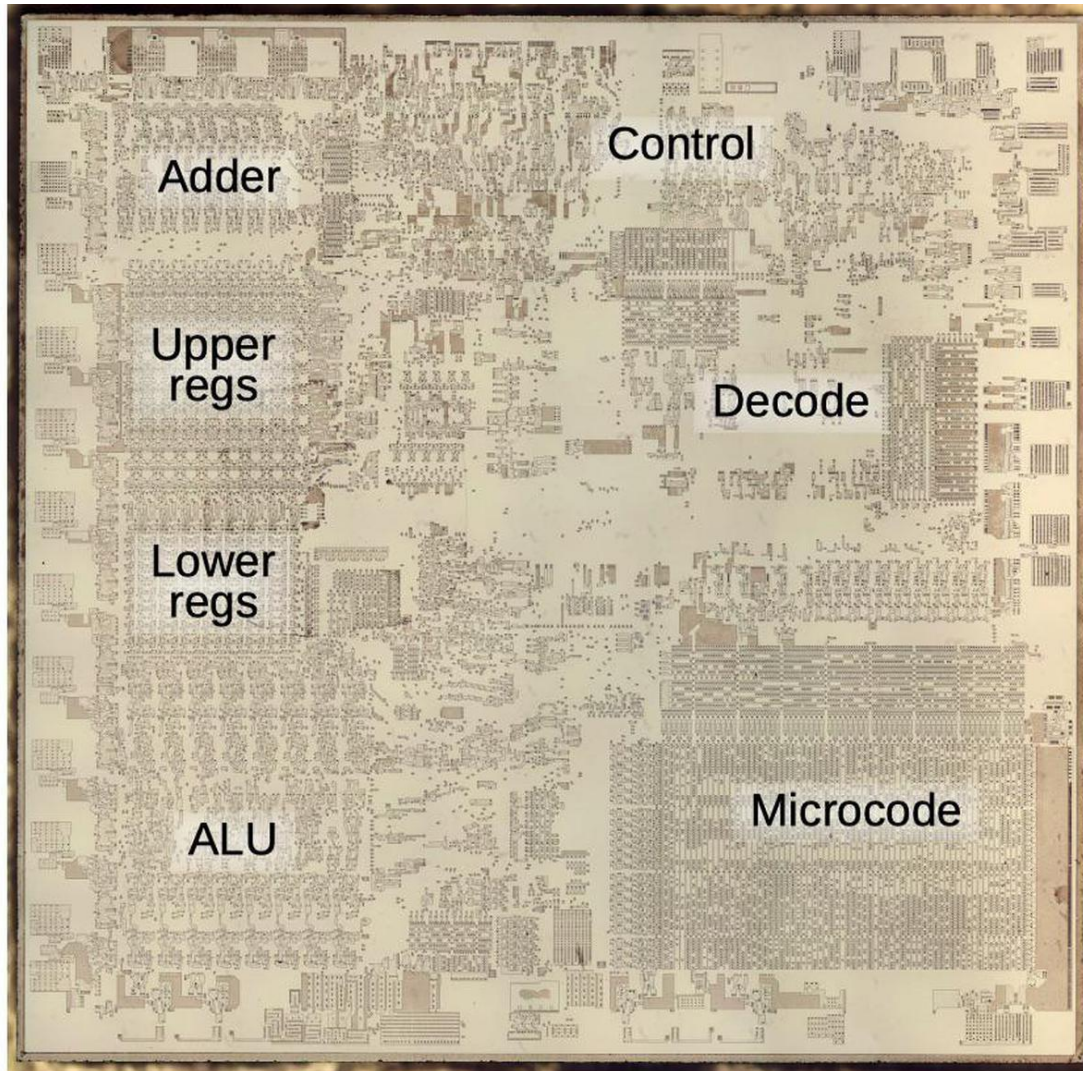


OVERVIEW OF CHIP FABRICATION

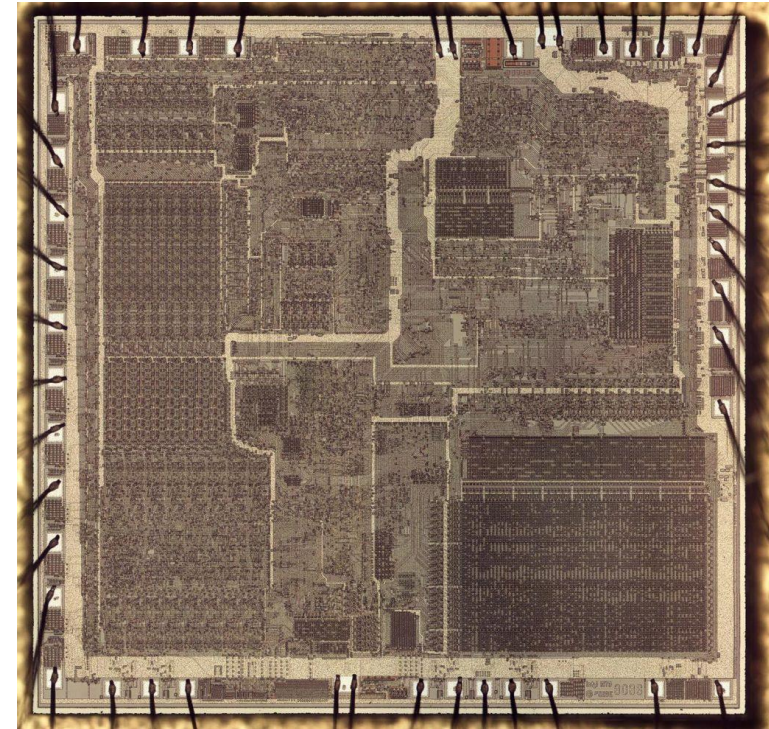
(COURTESY:BRANCH EDUCATION YOUTUBE)

Click to the Video on Chip Fabrication

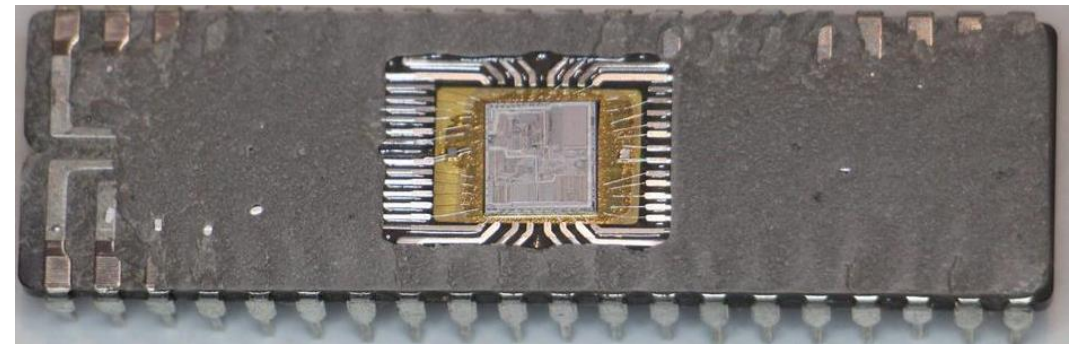
INTEL 8086



8086 IC/CHIP/DIE



BONDWIRES ON PADS



40 PIN DUAL-INLINE PACKAGE (DIP)

TRANSISTOR SCALING (MOORE'S LAW)

Moore's Law: The number of transistors on microchips doubles every two years

Moore's law describes the empirical regularity that the number of transistors on integrated circuits doubles approximately every two years. This advancement is important for other aspects of technological progress in computing – such as processing speed or the price of computers.

Our World
in Data

Transistor count

50,000,000,000

10,000,000,000

5,000,000,000

1,000,000,000

500,000,000

100,000,000

50,000,000

10,000,000

5,000,000

1,000,000

500,000

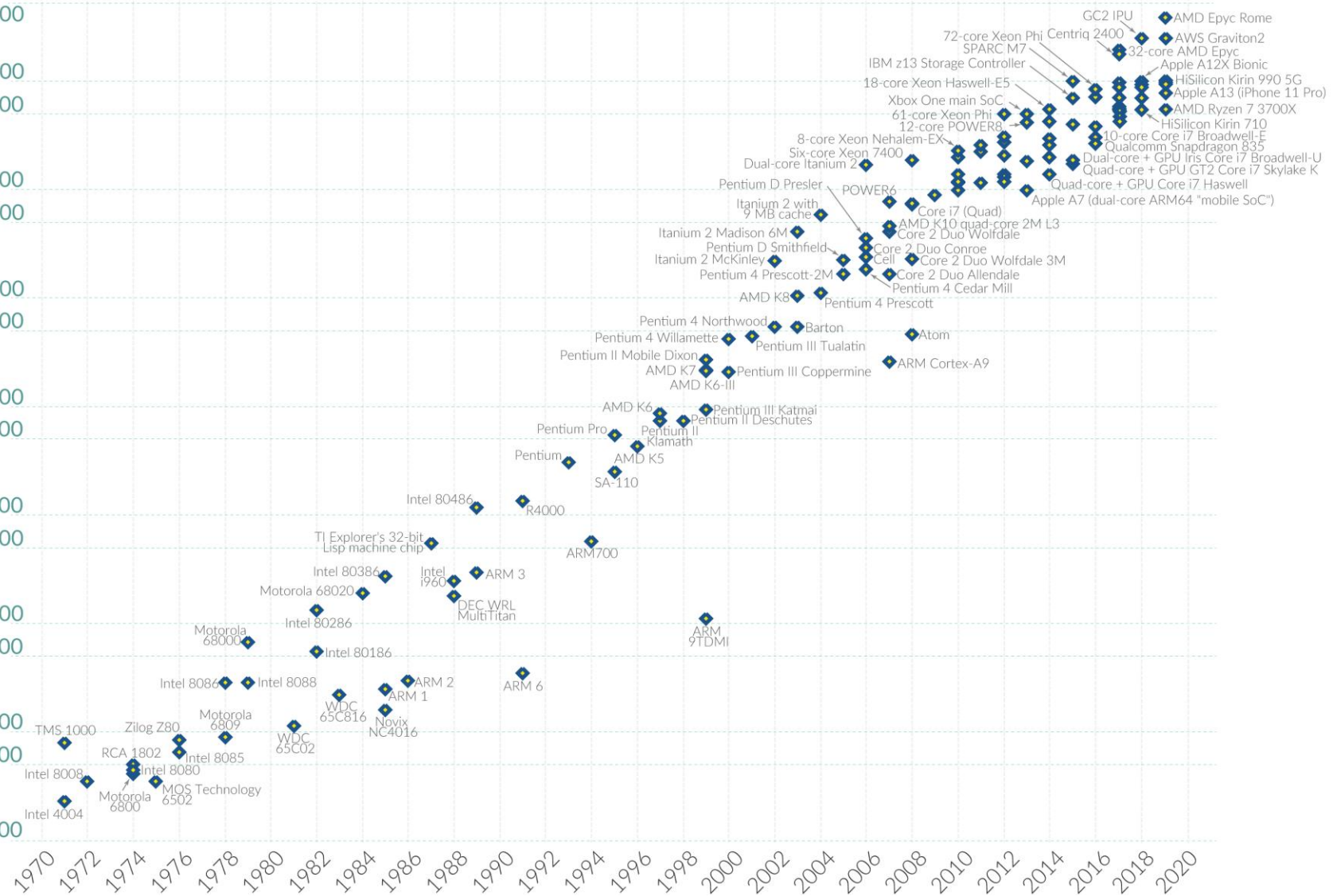
100,000

50,000

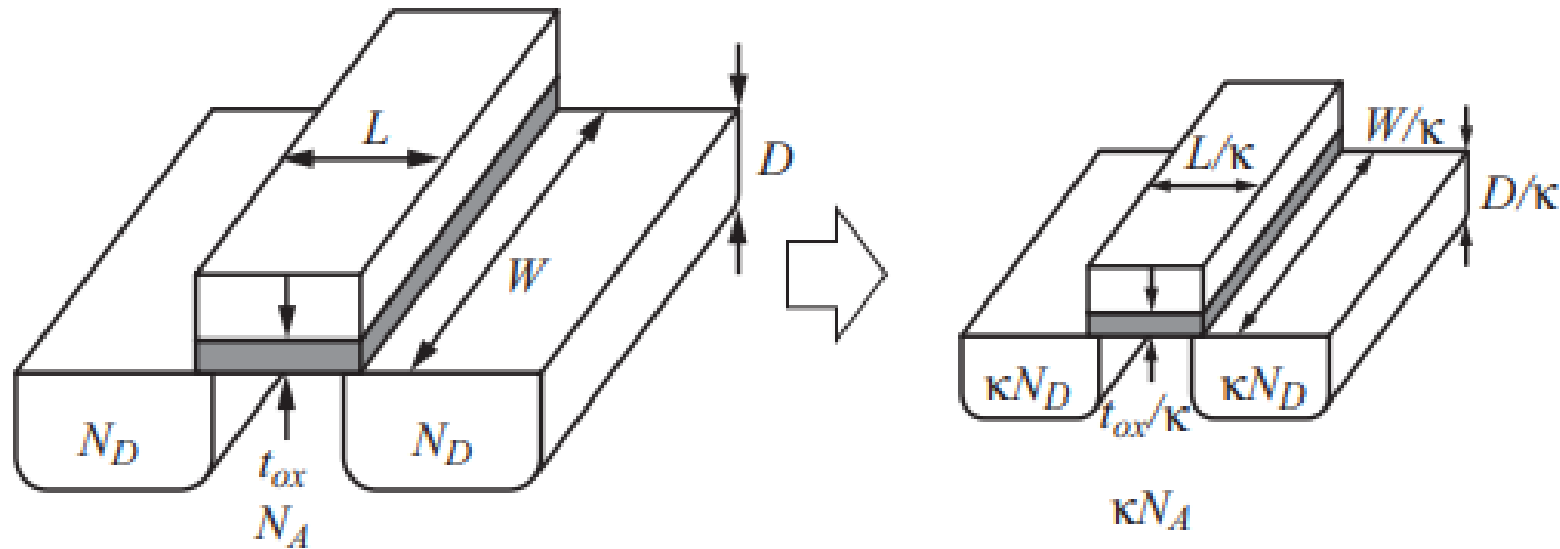
10,000

5,000

1,000



TRANSISTOR SCALING



- W : MOS Width, L : MOS Length (design choice)
- W_{min} : Minimum MOS Width, L_{min} : Minimum MOS Length
- t_{ox} : Oxide thickness (fixed for a given technology)
- N_D : Doping concentration (fixed for a given technology)
- κ : Scaling factor (from one technology to another)

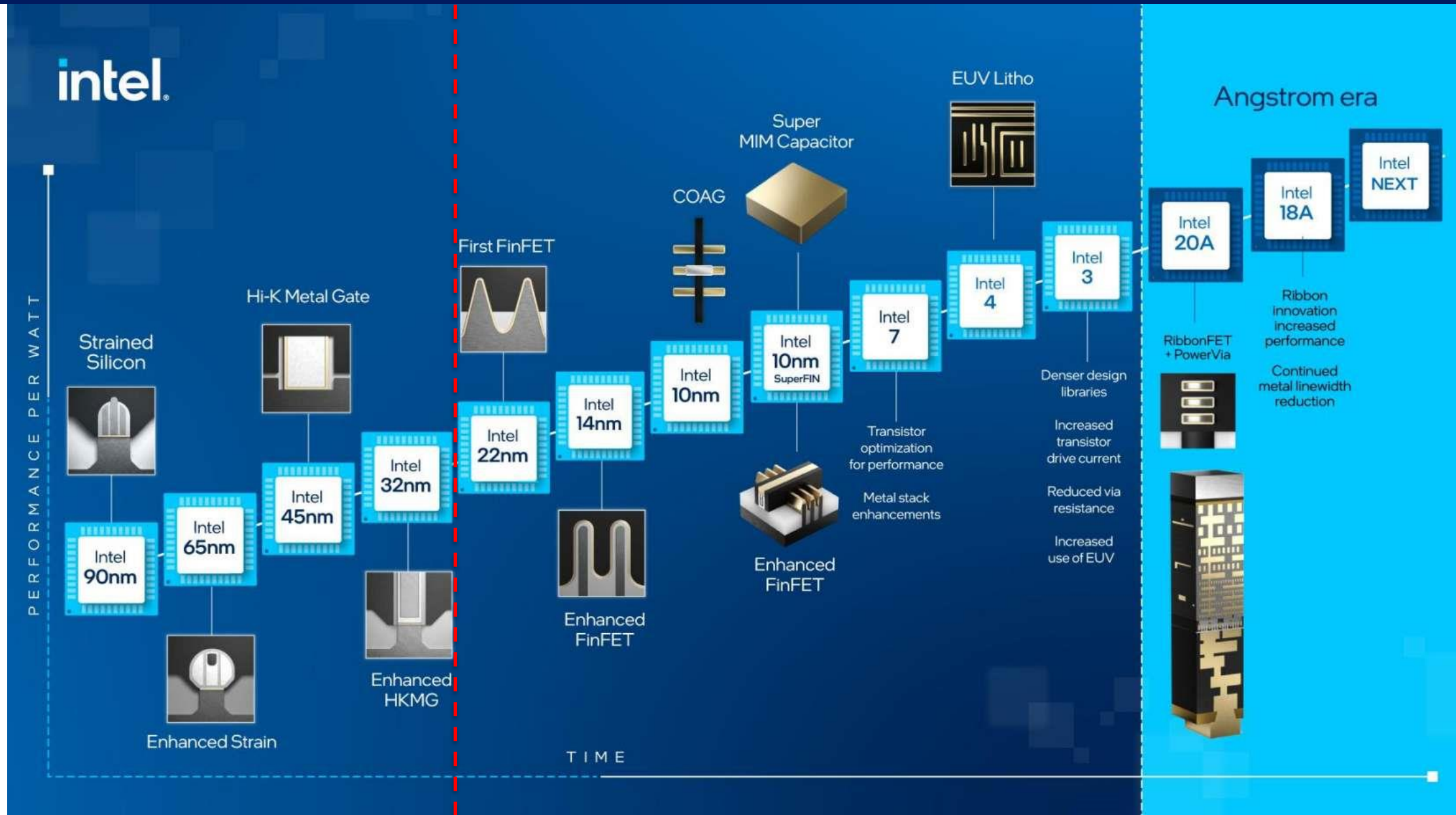
TRANSISTOR SCALING

- ❑ What are the benefits in technology scaling?
 - ❑ Transistors length becomes smaller → Faster
 - ❑ Circuits get Smaller & Faster
 - ❑ More transistors fit in a chip (same area)
 - ❑ Double advantage in performance: Speed and Density (increased functionality)

- ❑ If all dimensions (length, width of MOS) scale by a factor “ κ ”
 - ❑ Area shrinks by a factor κ^2
 - ❑ $\kappa = \sqrt{2}$, Area shrinks by half (remember Moore’s law)
 - ❑ The dimension/feature size is called a “Technology node”
 - ❑ Eg: 180nm → 130nm → 90nm → 65 nm → 45nm etc.



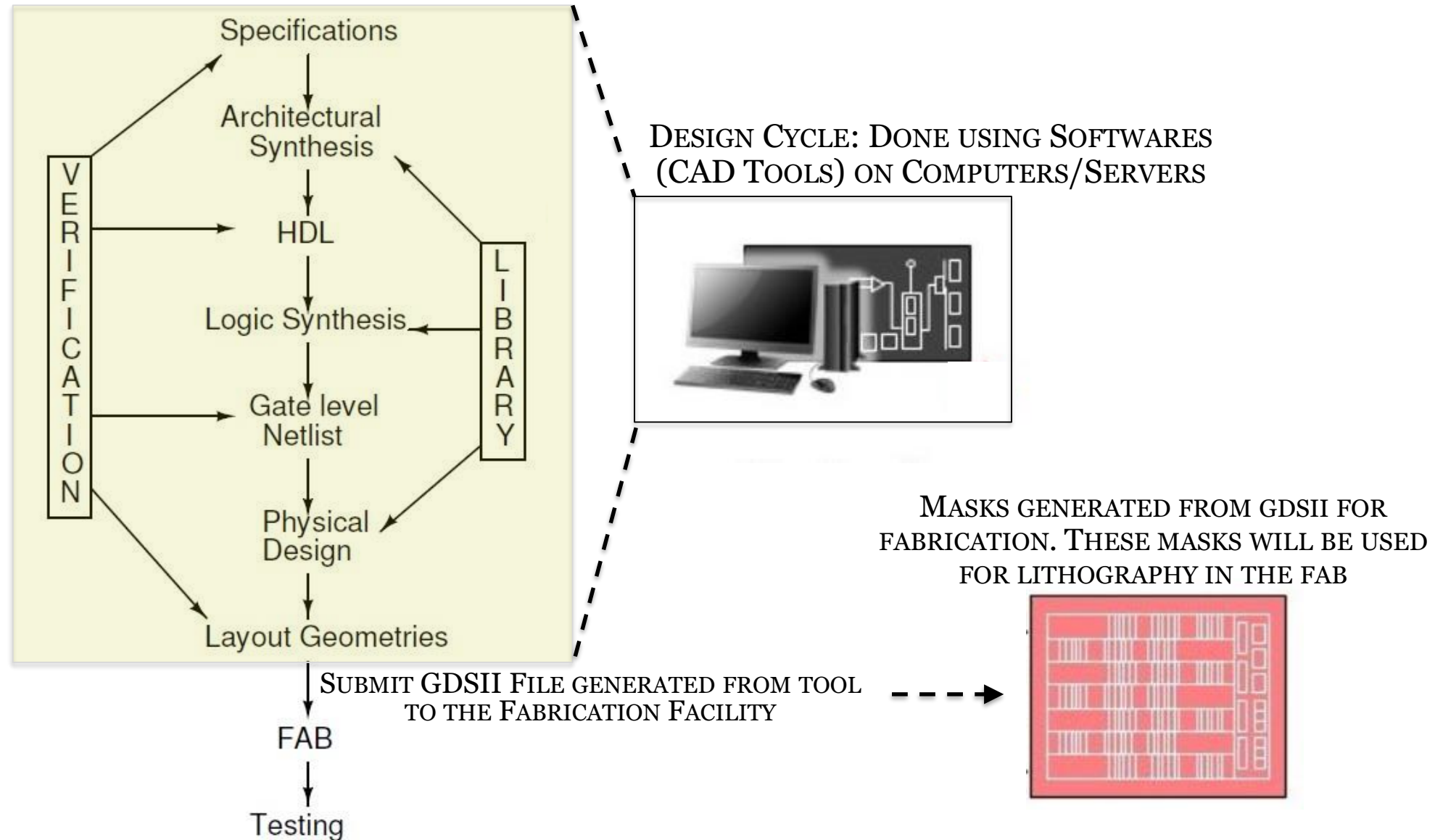
TRANSISTOR SCALING (LOOKING AHEAD)



COURTESY: INTEL

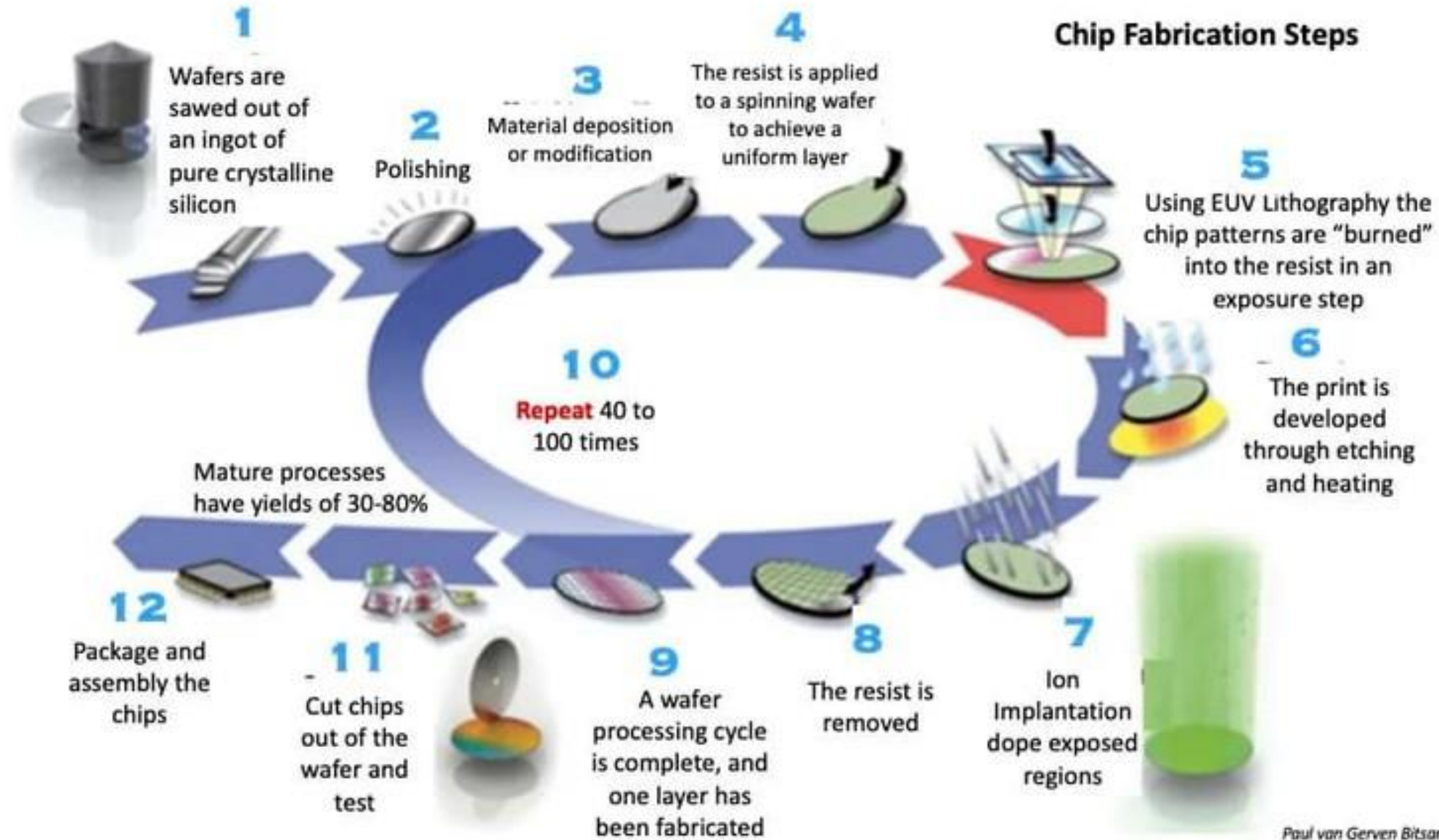


BRIEF OVERVIEW OF VLSI DIGITAL DESIGN



BRIEF OVERVIEW OF VLSI DIGITAL DESIGN: FAB

FAB STEPS COVERED IN EE669: VLSI TECHNOLOGY

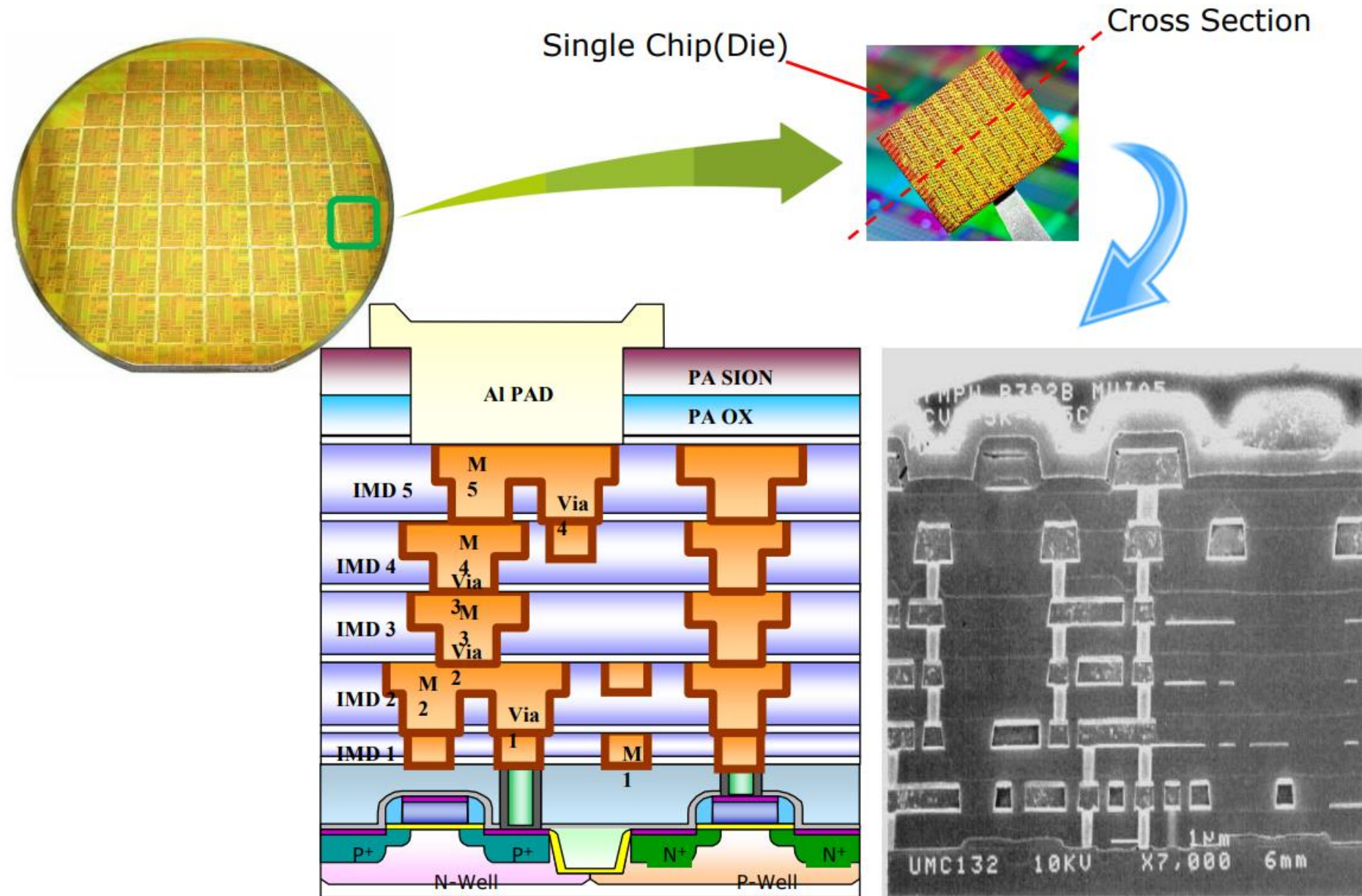


COURTESY: BITS&CHIPS

Paul van Gerven Bitsand Chips



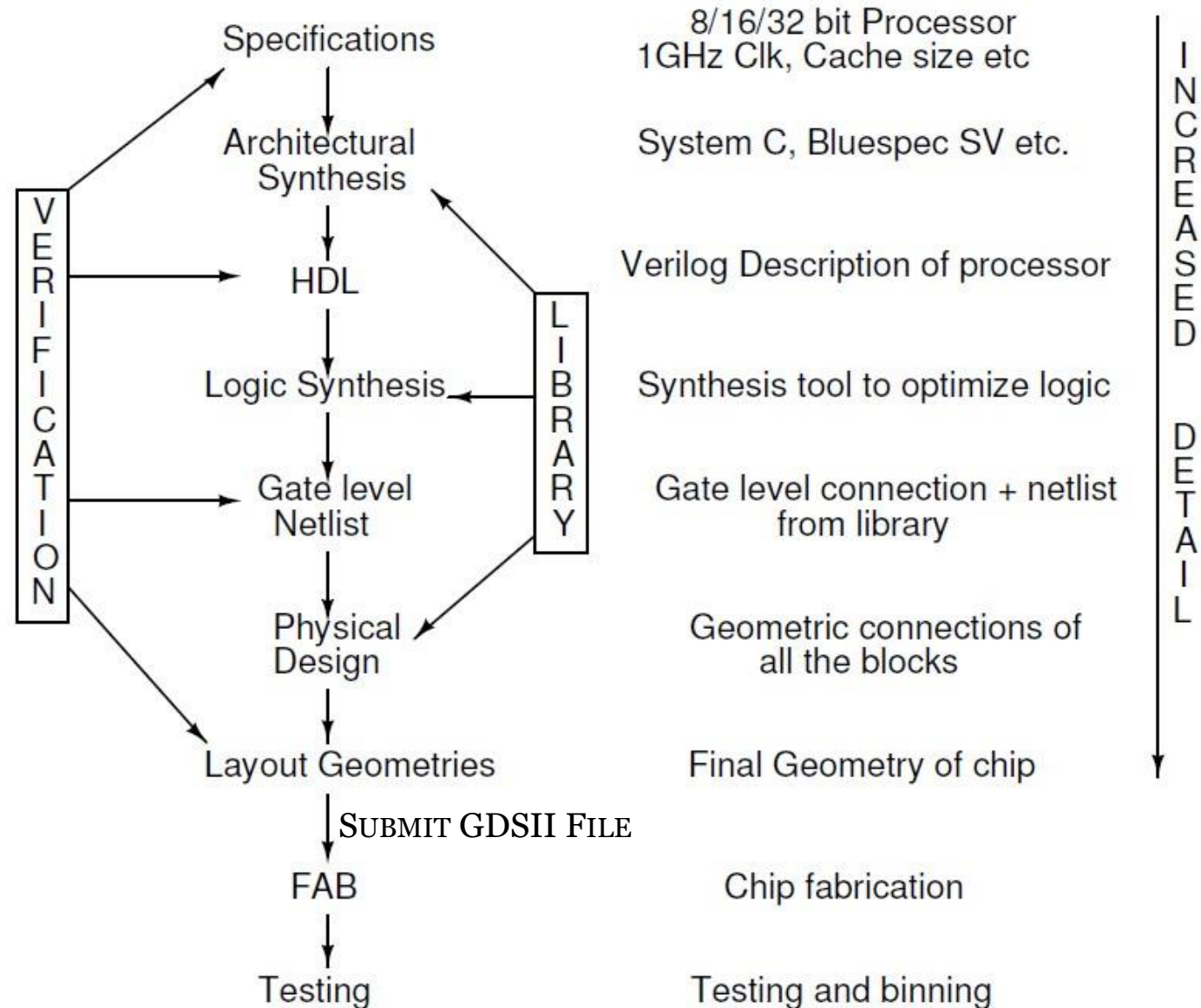
BRIEF OVERVIEW OF VLSI DIGITAL DESIGN: EXAMPLE DIE



COURTESY: INFINEON



BRIEF OVERVIEW OF VLSI DIGITAL DESIGN

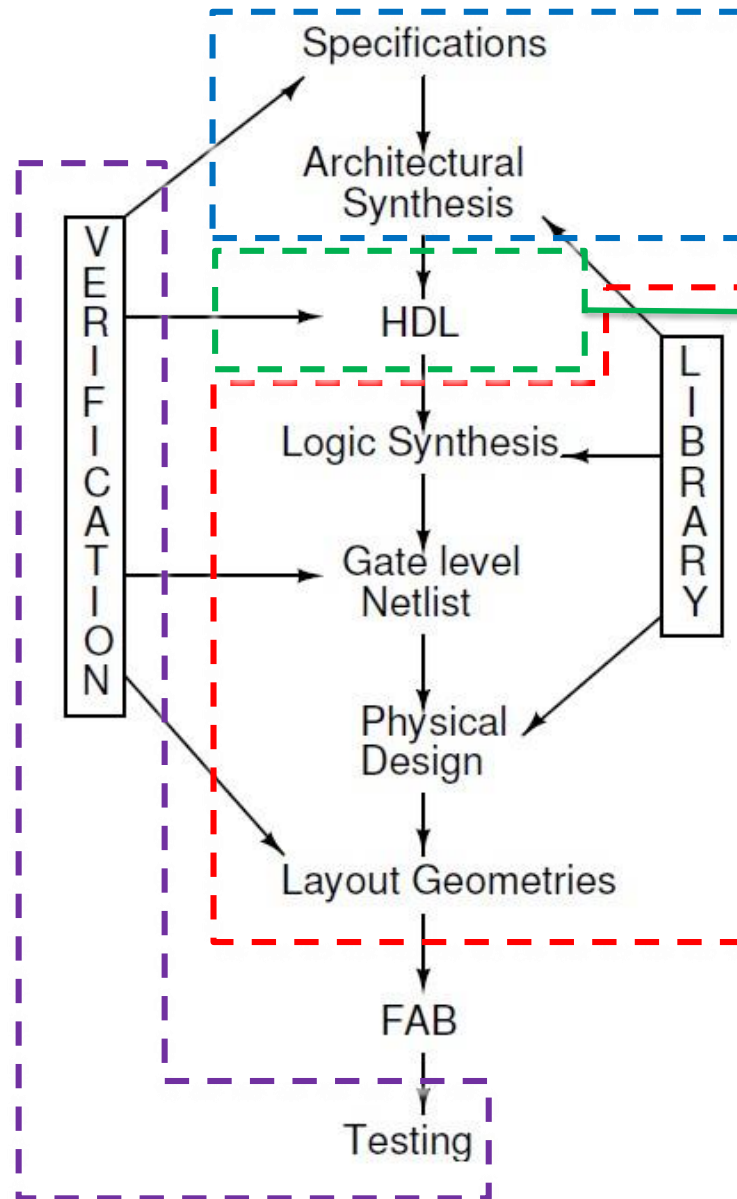


COURTESY: INTEL



WHAT ARE WE LEARNING IN THIS COURSE?

EE709: TESTING
& VERIFICATION



EE739: PROCESSOR DESIGN
EE789: ALGORITHMIC DESIGN OF
DIGITAL SYSTEMS

EE721: HARDWARE DESCRIPTION
LANGUAGES

EE671 – THIS COURSE!

PRE-MIDSEM: LIBRARY DEVELOPMENT

POST-MIDSEM: RTL TO FAB

COURSE WILL NOT COVER FPGA DESIGN – THIS WILL
BE TAKEN UP IN EE705 (VLSI DESIGN LAB)

COURTESY: INTEL

